

CHAPTER 2 TRANSIENT HEAT CONDUCTION

2.1 Lumped Parameter Model and the Thermal Network Method

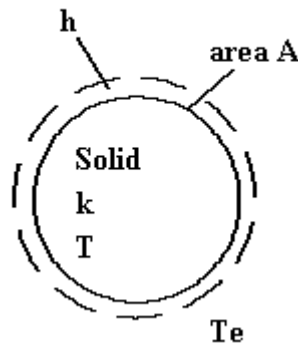
All materials can store heat. Therefore, when a temperature or heat flux change is imposed it takes some time to reach steady state. During this time, we must perform a transient analysis to determine temperatures and heat flows. For systems with negligible thermal resistance, we may perform a simplified analysis.

The Biot number (Bi) is a dimensionless number, equal to the ratio of the internal thermal resistance ($1/k$) to the surface thermal resistance ($1/h \cdot L$). This number determines whether lumped parameter analysis is applicable.

$$Bi = \frac{h \cdot L}{k} \quad \text{where } L \text{ is a characteristic length} \\ (L = \text{Volume} / \text{Area}).$$

If Bi is small (< 0.1), we can assume with reasonable accuracy that the body is isothermal, and lumped parameter analysis can be performed.

Consider the cooling of a resistance element in an electric heater at initial temperature T_0 exposed to an environment at T_e . Assume that the element is a cylindrical wire.



Objective: Determine $T(t)$

Initial condition: $T(t=0) = T_0$, Environment temp. = T_e

Given data:

$L := 0.5 \text{ m}$ wire length

$D := 0.001 \text{ m}$ diameter

$k := 374 \frac{\text{W}}{\text{m} \cdot \Delta^\circ\text{C}}$ thermal conductivity

$$c := 383 \frac{J}{kg \cdot \Delta^{\circ}C} \quad \text{specific heat capacity}$$

$$\rho := 8930 \frac{kg}{m^3} \quad \text{density}$$

$$h := 10 \frac{W}{m^2 \cdot \Delta^{\circ}C} \quad \text{heat transfer coefficient}$$

$$A := \pi \cdot D \cdot L \quad \text{surface area}$$

$$V := \pi \cdot \frac{D^2}{4} \cdot L \quad \text{wire volume}$$

$$L := \frac{V}{A} \quad \text{characteristic length}$$

$$Bi := h \cdot \frac{L}{k} = ?$$

$$T_o := 150 \Delta^{\circ}C \quad T_e := 40 \Delta^{\circ}C$$

Energy balance (Biot number < 0.1):

change in internal energy during time dt = net heat flow from body during dt

$$-C \cdot dT = (T - T_e) \cdot \frac{dt}{R}$$

where

$$C := c \cdot \rho \cdot V \quad \text{thermal capacitance of body}$$

$$R := \frac{1}{A \cdot h} \quad \text{surface resistance}$$

Therefore

$$\frac{d(T - T_e)}{T - T_e} = -\frac{dt}{R \cdot C}$$

Integrating both sides and applying the initial condition with

$$i := 0..5$$

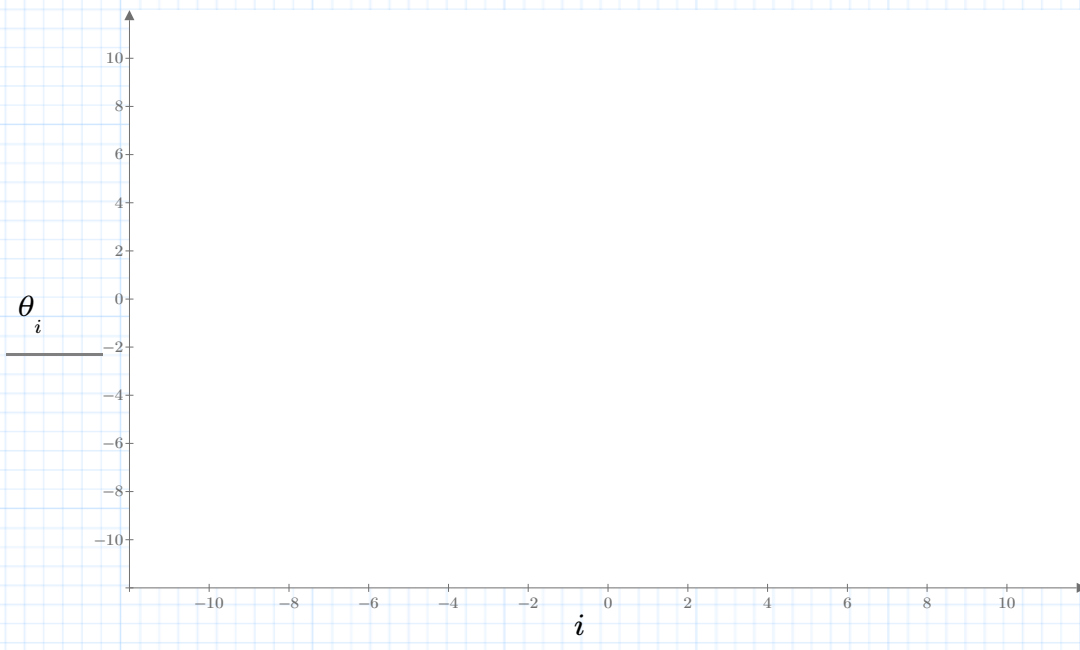
$$t_i := i \cdot R \cdot C \quad t_1 = ? \quad \text{time constant}$$

Let

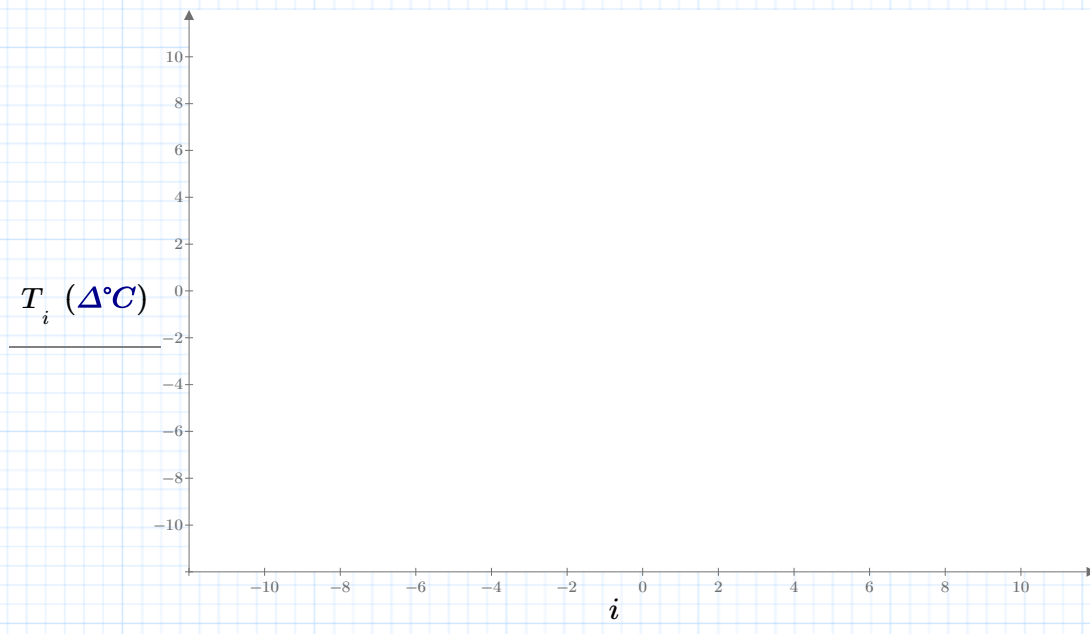
$$\theta = \frac{T - T_e}{T_o - T_e} \quad \text{dimensionless temperature}$$

Solution:

$$\theta_i := \exp\left(-\frac{t_i}{R \cdot C}\right)$$



$$T_i := \theta_i \cdot (T_o - T_e) + T_e$$



Note that 63% of the change occurs after one time interval (from $i=0$ to $i=1$), i.e. a temperature drop of $0.63 \cdot (T_o - T_e)$

$$\theta_0 - \theta_1 = 18.075 \text{ 1\%} \quad \frac{T_0 - T_1}{T_0 - T_5} = \begin{bmatrix} 1 \\ 2 \\ 3 \end{bmatrix} \text{ 1\%}$$

Thermal Network Model

The body can be modeled with an isothermal capacitance C in parallel with a resistance R (equal to $1/A \cdot h$) both connected to the environment at temperature T_e .

Note that the capacitance (or capacitances) in a thermal network are always modeled as connected between a reference temperature (usually the environment temperature T_e) and their own temperature T . Heat flow into the capacitance means flow from T to T_e .

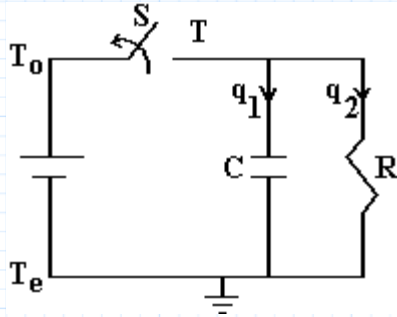
The initial condition $T(t=0) = T_o$ can be simulated by a "battery" $T_o - T_e$ connected through a switch S to the capacitance, and also connected to the reference node.

The constitutive equation for a thermal resistance is simply

$$q = \frac{T_{hot} - T_{cold}}{R}$$

Similarly, for a capacitance we have

$$q = C \cdot \frac{d}{dt} (T - T_e) \quad \text{where } T_e \text{ is constant}$$



Switch S opens at $t = 0$. Energy balance at T:

$$\text{Heat flow into } C + \text{Heat flow to } R = 0$$

$$\text{or} \quad q_1 + q_2 = 0$$

$$C \cdot \frac{d}{dt} (T - T_e) + \frac{T - T_e}{R} = 0$$

$$\frac{d}{dt} (T - T_e) + \frac{T - T_e}{R \cdot C} = 0$$

The same solution as before is obtained (initial condition $T(0) = T_0$).

In **Chapter 9**, we will see how a transient thermal network of a room is developed and solved to determine heating/cooling loads and room temperatures.